PCN Number: 20230801001.1							ate:	August 02, 2023				
Title: Qualification of Cu as an alternate bond wire for select devices												
Customer Contact: Change Management Team Dept: Quality Services												
Proposed 1 <sup>st</sup> Ship Date: Oct 31, 2023  Sample Requests accepted until: Sept 2, 2023								2, 2023				
*Sample requests received after Sept 2, 2023 will not be supported.												
☐ Assembly Sit	e		Design [			Wafer Bump Material						
Assembly Pro		☐ Data Sheet			Wafe	Wafer Bump Process						
Assembly Ma		☐ Part number change				Wafer Fab Site						
☐ Mechanical S	1 <u> </u>	Test Site			_	Wafer Fab Material						
☐ Packing/Shipping/Labeling			Test Process			Wafer Fab Process						
PCN Details												
Description of Change:												
This PCN is to inform of an alternative bond qualification for the devices in the product affected section as follows:  Current Additional												
				Current		Additional						
	Bond wire, neter		Au, 1.3 mils			Cu, 1.3 mil						
Reason for Char	ige:											
Continuity of supply.												
1) To align with world technology trends and use wiring with enhanced mechanical and												
electrical prop												
2) Maximize flexibility within our Assembly/Test production sites.												
3) Cu is easier to obtain and stock												
Anticipated imp	act on Fori	m, Fit, Fun	ction,	Quality or Reliab	ility	(posit	ive / n	egative):				
None												
Impact on Environmental Ratings												
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.												
RoHS		REACH	ł	Green Sta	atus		IE	C 62474				
No Change		No Change	ange 🛛 No Chang			Σ	No C	hange				
Changes to product identification resulting from this PCN:												
None												
<b>Product Affected</b>	d:											
LMG3410R050RW	'HR LMG	3410R070R	WHT	LMG3411R050R\	NHR	LM	 G3411R	.070RWHT				
LMG3410R050RW		3410R150R		LMG3411R050R\				150RWHR				
	ĺ			LMG3411R070R\				.150RWHT				
LMG3410R070RW	TIN LING	3410R150R	V V I I I	FILIGOATTKO\OK/	/V I I 🎮	الاالا	つつみTTK	TOCANIII				

## **Qualification Report**

### Polaris LMG3410R050RWHR

### Approve Date 10-July-2023

#### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: LMG3410R050RWHR	QBS Reference: LMG3422R030RQZT	QBS Reference: LMG3422R030RQZT
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	1/75/0	2/157/0
HAST	A2	Biased HAST	130C/85%RH	96 Hours	1/77/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	1/77/0	1/80/0	3/240/0
TC	A4	Temperature Cycle	-40C/125C	850 Cycles	-	1/80/0	2/160/0
TC	A4	Temperature Cycle	-55C/150C	560 Cycles	1/77/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	1/80/0	2/157/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	1/800/0	2/1610/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-
FTY	E6	Final Test Yield	-	-	1/PASS	-	-

- OBS: Qual By Similarity
- Qual Device LMG3410R050RWHR is qualified at NOT CLASSIFIED 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2306-018

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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